

VMEC EQUIPMENT/SEED GRANT RESEARCH SUMMARY

PROPOSAL TITLE:

Ultralow-power straintronic switch implemented with a nanomagnet and a topological insulator for “processor in memory” architectures

RESEARCH SUMMARY:

Processor-In-Memory (PiM) architectures are designed to circumvent the present day “Von Neumann bottleneck” in conventional silicon computing. This bottleneck arises from the physical separation of processor and memory cores, and the resulting delay in data transfer between the two. The data transfer link is also wasteful of energy and a target for cyberattacks. PiM architectures circumvent this shortcoming by carrying out processing within the memory core, thereby eliminating the need for the link.

We propose to lay the groundwork for a new PiM architecture proposed by one of the PIs (AG) [1], involving emerging materials and their novel underlying physics. The critical element of this architecture is a novel switch that exploits the reciprocal interaction between a ferromagnetic (FM) film grown on a 3-D topological insulator (TI) film whose bulk is insulating but surface states are conducting. The FM layer is designed to have perpendicular magnetic anisotropy, which makes the magnetization point out of the magnet’s plane. By applying a strain to the FM using a piezoelectric layer, the magnetization can be moved from out- to in-plane, which will close an energy gap in the TI’s surface states and increase the surface current, thereby switching the device from OFF to ON. Such a device can act as a row-column selector. The random addressed TI-FM cell can then be enabled to write information onto a magnetic storage element, subsequent to which, one can use a sense amplifier to execute key Boolean logic gate operations directly and in parallel on entire rows of locally stored data. This VMEC proposal will establish the computational infrastructure for studying the performance metrics of this device, which will also be fabricated and characterized to demonstrate the out-of-plane to in-plane switching of the magnet’s magnetization due to strain, and ensuing modulation of the TI-FM heterostructure’s overall conductance. Since it could take only a few tens mV to generate the strain required to switch, the switching action will be extremely energy efficient (few aJ expended to switch). and take place in less than 1 ns, which promises a clock rate of ~GHz.

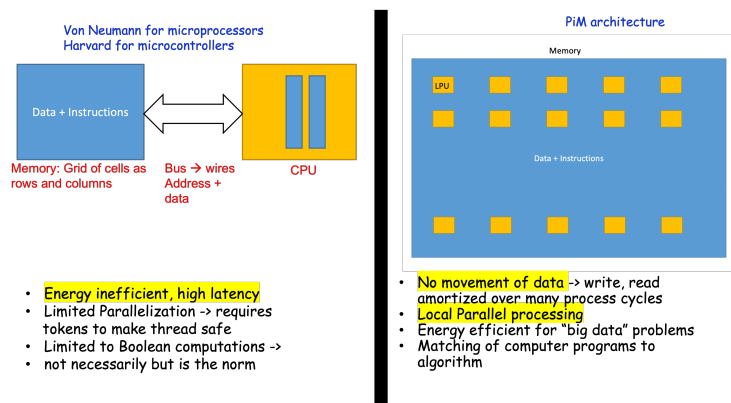


Fig. 1: Comparison between von-Neumann and PiM architectures

Research Background: The memory hierarchy.

Conventional Von Neumann architecture has separate memory and logic elements with data buses connecting the two. Since memory scales slower than logic, this creates a ‘memory wall’ (weaknesses summarized in Fig. 1). In contrast, a PiM architecture involves no data movement between logic and memory cores, and relies on local parallel processing of data. Designing an

1: Fabrication of the device using reactive ion etching. The electrical contacts will be delineated with optical lithography for relatively large structures and e-beam lithography for small structures. The electrode materials will be Al or Au. All processing steps will be carried out in the Virginia Microelectronics Center cleanroom at VCU.

2: The switching action will be demonstrated by measuring the transfer characteristics of the device (current flowing between the source and drain contacts in Fig. 3 as a function of the gate voltage). The gate voltage generates strain in the piezoelectric layer which rotates the magnetization of the magnetic layer from out of plane to in-plane and closes the energy gap in the TI, thereby increasing the source to drain current. These measurements will be made using a Semiconductor Parameter Analyzer at VCU. The obtained characteristics will yield measurement of the current ON/OFF ratio for maximum strain and also the device transconductance.

Expenses : The funding will be utilized to pay the annual stipend of a graduate student at VCU who will carry out all fabrication and measurements. An amount of \$5 K has been budgeted for material cost and lab charges. Computational cost has been budgeted at \$12 K.

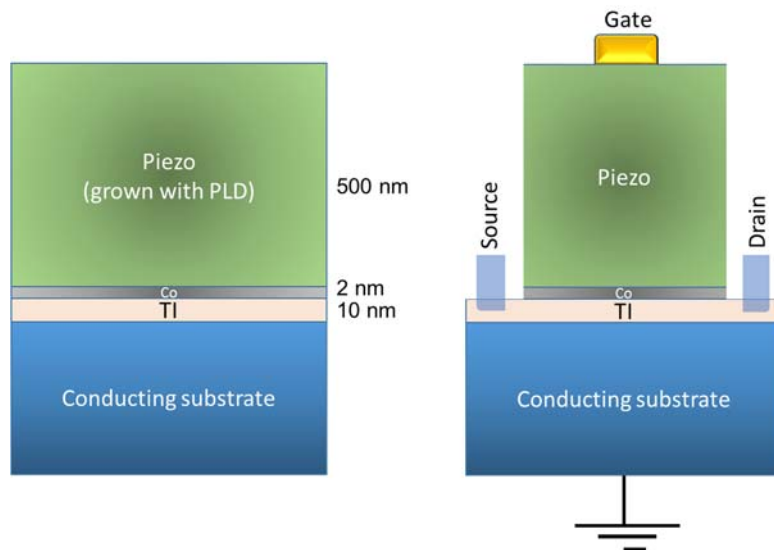


Fig. 3: Schematic of the structure to be fabricated.

Impact on the Commonwealth :

There are numerous industries in the State of Virginia that can benefit from the research proposed here. That includes VMEC members like BAE Systems and Micron, who are heavily involved with silicon platforms for computing and information processing. As Virginia poises herself to play a major role in semiconductors buoyed by the CHIPS act established by the Congress and the Senate, novel devices and architectures will garner increasing attention. The PiM architecture discussed here leads to

several advances – increased energy efficiency, better resilience against cyberattacks and high speed computing. There is a drive to move data processing out of the cloud into the edge for internet of things and this research is synergistic with this vision. Two premier research universities in Virginia, with strong programs in semiconductor devices, are collaborating in this proposal to innovate a new device that can lead to disruptive technologies. Additionally, we expect to involve undergraduate students working on capstone projects in some elements of this research. These trained students will constitute a valuable pool of skilled workers in the State of Virginia.

References :

1. H. Vakili, et al., www.arXiv.org, article 2203.14389 (2022)
2. N. D'Souza, et al., Nano Letters, 16, 1069-1075 (2016).